



Material Content Data Sheet



Sales Product Name	TLE7258LE			Issued	24. January 2018			
MA#	MA001798322							
Package	PG-TSON-8-1			Weight*	26.84 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.828	3.08	3.08	30848	30848
leadframe	inorganic material	phosphorus	7723-14-0	0.003	0.01		110	
	non noble metal	zinc	7440-66-6	0.012	0.04		440	
	non noble metal	iron	7439-89-6	0.236	0.88		8797	
wire	non noble metal	copper	7440-50-8	9.586	35.72	36.65	357182	366529
	non noble metal	copper	7440-50-8	0.038	0.14	0.14	1400	1400
	encapsulation	organic material	carbon black	1333-86-4	0.031	0.11		1143
plastics	plastics	epoxy resin	-	1.580	5.89		58866	
	inorganic material	silicondioxide	60676-86-0	13.728	51.16	57.16	511505	571514
leadfinish	non noble metal	tin	7440-31-5	0.382	1.42	1.42	14241	14241
plating	noble metal	silver	7440-22-4	0.043	0.16	0.16	1620	1620
glue	plastics	epoxy resin	-	0.093	0.35		3462	
	noble metal	silver	7440-22-4	0.279	1.04	1.39	10386	13848
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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